Freescale Semiconductor

MPXHZ6130A
Rev 1, 05/2010

Media Resistant and High Temperature Accuracy Integrated Silicon Pressure Sensor for Measuring Absolute Pressure, On-Chip Signal Conditioned, Temperature Compensated and Calibrated

MPXHZ6130A Series

15 to 130 kPa (2.2 to 18.9 psi)
0.2 to 4.8 V Output

The MPXHZ6130A series sensor integrates on-chip, bipolar op amp circuitry and thin film resistor networks to provide a high output signal and temperature compensation. The sensor's packaging has been designed to provide resistance to high humidity conditions as well as common automotive media. The small form factor and high reliability of on-chip integration make the Freescale Semiconductor, Inc. pressure sensor a logical and economical choice for the system designer.

The MPXHZ6130A series piezoresistive transducer is a state-of-the-art, monolithic, signal conditioned, silicon pressure sensor. This sensor combines advanced micromachining techniques, thin film metallization, and bipolar semiconductor processing to provide an accurate, high level analog output signal that is proportional to applied pressure.

Features

- 1.5% Maximum Error Over 0° to 85°C
- Resistant to High Humidity and Common Automotive Media
- Improved Accuracy at High Temperature
- Ideally suited for Microprocessor or Microcontroller-Based Systems
- Temperature Compensated from -40° to +125°C
- Durable Thermoplastic (PPS) Surface Mount Package

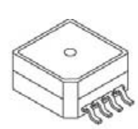
Application Examples

- Aviation Altimeters
- Industrial Controls
- Engine Control/Manifold Absolute Pressure (MAP)
- Weather Stations and Weather Reporting Devices

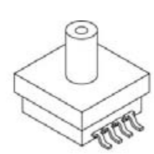
ORDERING INFORMATION

Device Name	Package Options	Case No.	# of Ports			Pressure Type			Device Marking
			None	Single	Dual	Gauge	Differential	Absolute	
Super Small Outline Package (MPXHZ6130A Series)									
MPXHZ6130A6U	Rail	1317	•					•	MPXHZ6130A
MPXHZ6130AC6U	Rail	1317A		•				•	MPXHZ6130A

SUPER SMALL OUTLINE PACKAGES



MPXHZ6130A6U
CASE 1317



MPXHZ6130AC6U
CASE 1317A

Operating Characteristics

Table 1. Operating Characteristics (V_S = 5.0 Vdc, T_A = 25°C unless otherwise noted, P1 > P2.

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range		P_{OP}	15	—	130	kPa
Supply Voltage[1]		V_S	4.75	5.0	5.25	Vdc
Supply Current		I_o	—	6.0	10	mAdc
Minimum Pressure Offset[2] @ V_S = 5.0 Volts	(0 to 85°C)	V_{off}	0.132	0.200	0.268	Vdc
Full Scale Output[3] @ V_S = 5.0 Volts	(0 to 85°C)	V_{FSO}	4.632	4.700	4.768	Vdc
Full Scale Span[4] @ V_S = 5.0 Volts	(0 to 85°C)	V_{FSS}	4.365	4.500	4.635	Vdc
Accuracy[5]	(0 to 85°C)	—	—	—	±1.5	$\%V_{FSS}$
Sensitivity		V/P	—	39.2	—	mV/kPa
Response Time[6]		t_R	—	1.0	—	ms
Warm-Up Time[7]		—	—	20	—	ms
Offset Stability[8]		—	—	±0.25	—	$\%V_{FSS}$

1. Device is ratiometric within this specified excitation range.
2. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
3. Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
4. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
5. Accuracy is the deviation in actual output from nominal output over the entire pressure range and temperature range as a percent of span at 25°C due to all sources of error including the following:
   - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
   - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from minimum or maximum rated pressure at 25°C.
   - TcSpan: Output deviation over the temperature range of 0° to 85°C, relative to 25°C.
   - TcOffset: Output deviation with minimum pressure applied, over the temperature range of 0° to 85°C, relative to 25°C.
6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the pressure has been stabilized.
8. Offset Stability is the product's output deviation when subjected to 1000 cycles of Pulsed Pressure, Temperature Cycling with Bias Test.

Maximum Ratings

Table 2. Maximum Ratings[1]

Rating	Symbol	Value	Units
Maximum Pressure (P1 > P2)	P_{max}	400	kPa
Storage Temperature	T_{stg}	-40° to +125°	°C
Operating Temperature	T_A	-40° to +125°	°C
Output Source Current @ Full Scale Output[2]	I_o+	0.5	mAdc
Output Sink Current @ Minimum Pressure Offset[2]	I_o-	-0.5	mAdc

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.
2. Maximum Output Current is controlled by effective impedance from V_{OUT} to Gnd or V_{OUT} to V_S in the application circuit.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

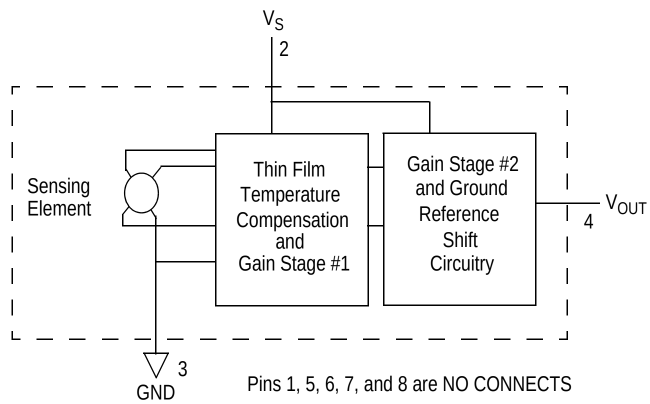


Figure 1. Fully Integrated Pressure Sensor Schematic

On-chip Temperature Compensation and Calibration

Figure 4 shows the sensor output signal relative to pressure input. Typical minimum and maximum output curves are shown for operation over 0 to 85°C temperature range. The output will saturate outside of the rated pressure range.

A gel die coat isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm. The gel die coat and durable polymer package provide a media resistant barrier that allows the sensor to operate reliably in high humidity conditions as well as environments containing common automotive media. Contact the factory for more information regarding media compatibility in your specific application.

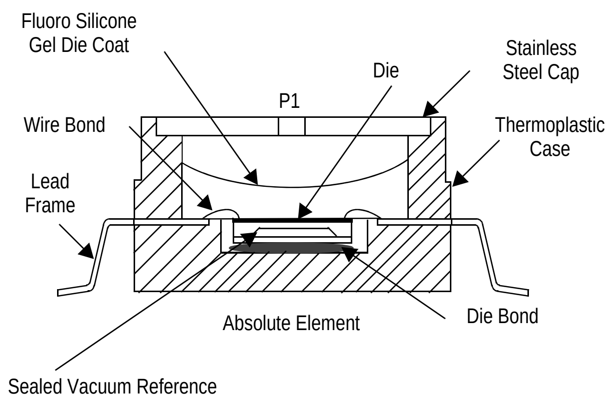


Figure 2. Cross Sectional Diagram SSOP (not to scale)

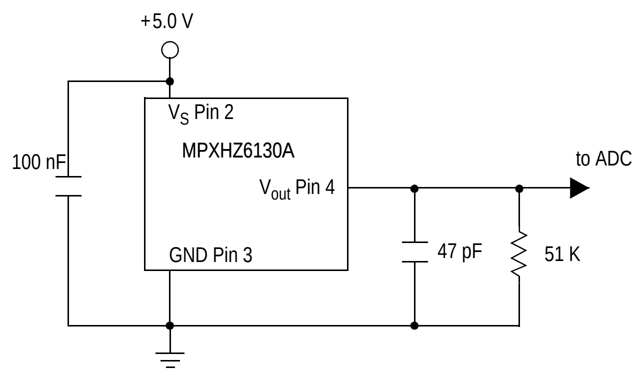


Figure 3. Typical Application Circuit (Output Source Current Operation)

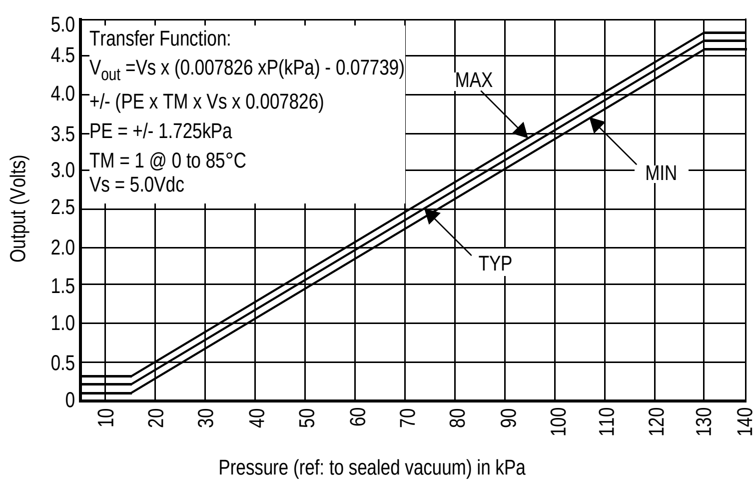
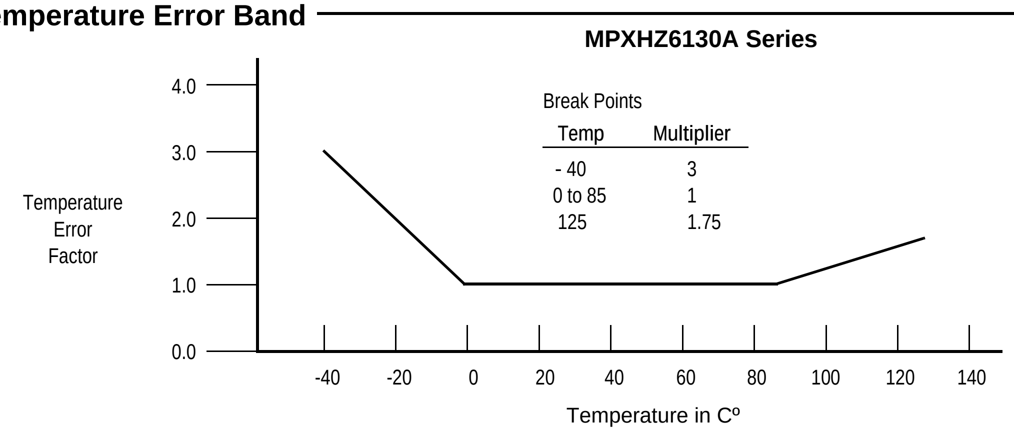


Figure 4. Output vs. Absolute Pressure

Transfer Function (MPXHZ6130A)

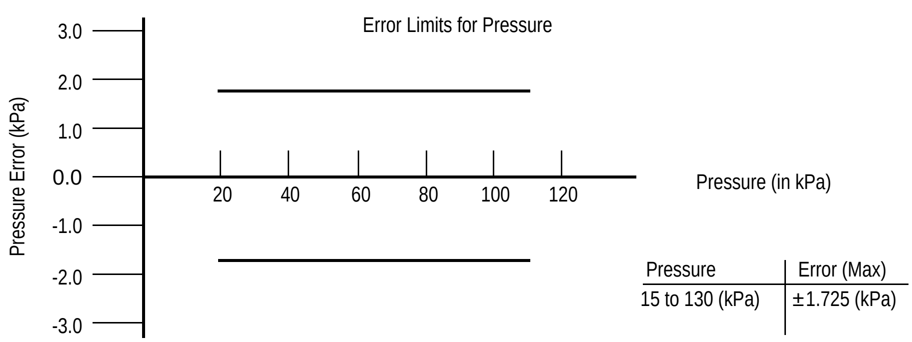
Nominal Transfer Value: $V_{out} = V_S \times (0.007826 \times P(kPa) - 0.07739)$
$\pm$ (Pressure Error x Temp. factor x $0.007826 \times V_S$)
$V_S = 5.0 \pm 0.25$ Vdc

Temperature Error Band



NOTE: The Temperature Multiplier is a linear response from 0ºC to -40ºC and from 85ºC to 125ºC

Pressure Error Band



MINIMUM RECOMMENDED FOOTPRINT FOR SUPER SMALL PACKAGES

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor package must be the correct size to ensure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self-align when subjected to a solder reflow process. It is always recommended to fabricate boards with a solder mask layer to avoid bridging and/or shorting between solder pads, especially on tight tolerances and/or tight layouts.

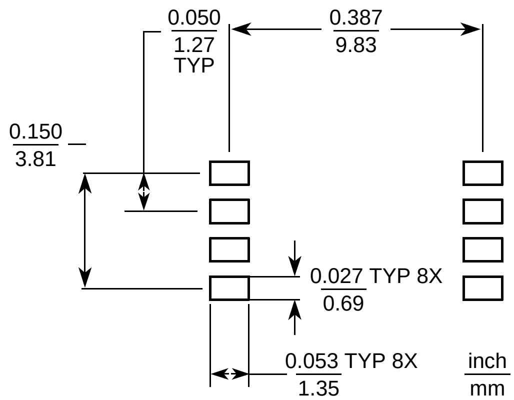
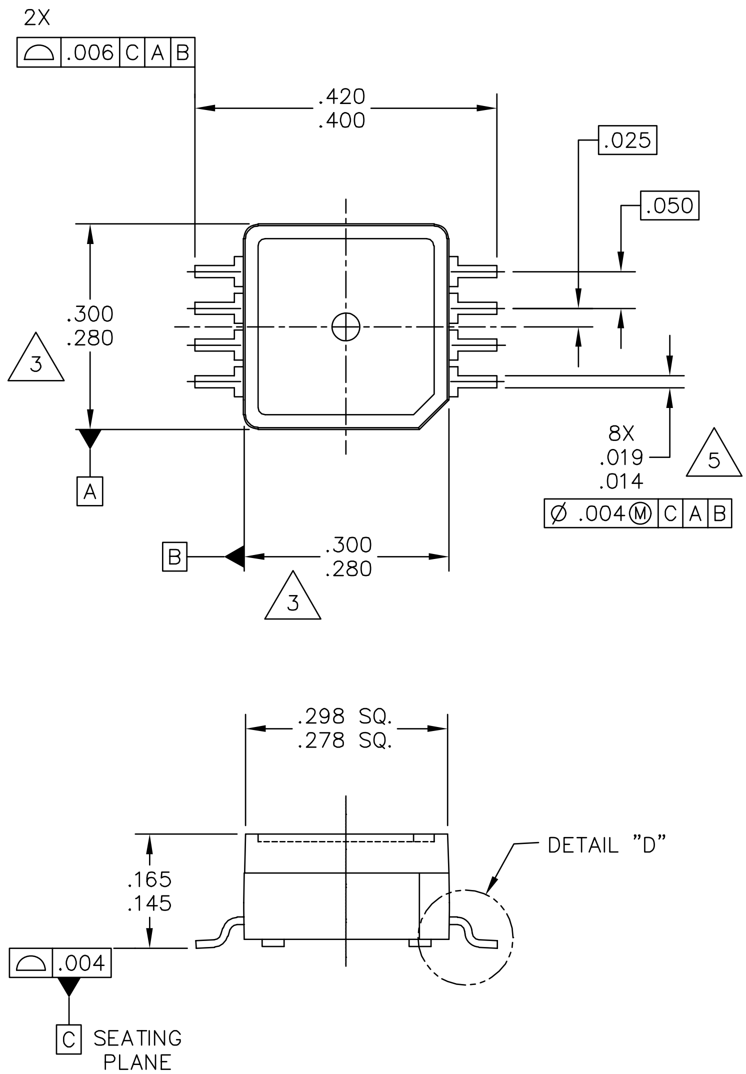


Figure 5. SSOP Footprint (Case 1317 and 1317A)

PACKAGE DIMENSIONS



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TITLE: 8 LEAD SSOP	DOCUMENT NO: 98ARH99066A	REV: F
	CASE NUMBER: 1317–04	24 MAY 2005
	STANDARD: NON–JEDEC	

CASE 1317-04
ISSUE F
SUPER SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS

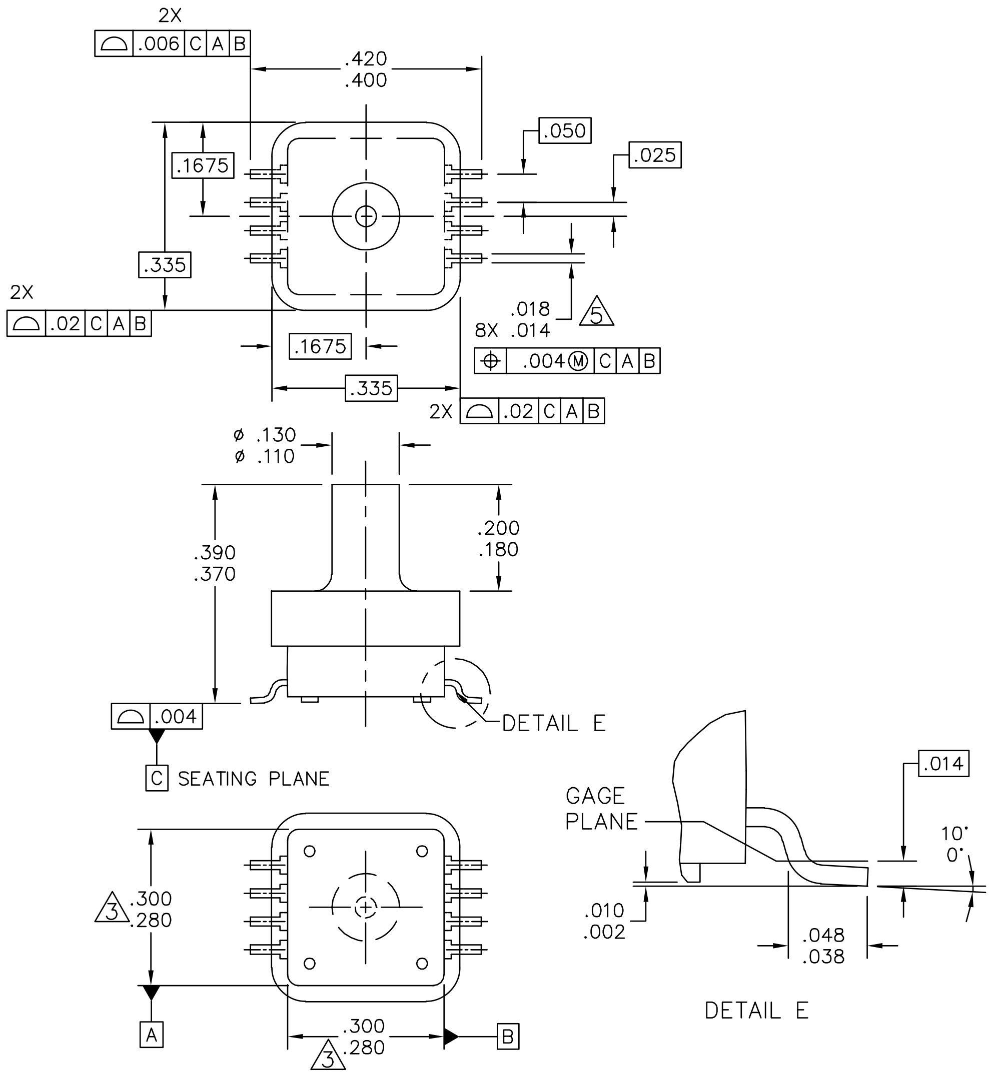
NOTES:

1. ALL DIMENSIONS IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. (△) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006 INCHES PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
5. (△) DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 INCHES MAXIMUM.

	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 8 LD, PORTED SSOP	DOCUMENT NO: 98ARH99089A		REV: D
	CASE NUMBER: 1317A–04		26 OCT 2006
	STANDARD: NON–JEDEC		

CASE 1317-04
ISSUE F
SUPER SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS



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TITLE: 8 LD, PORTED SSOP	DOCUMENT NO: 98ARH99089A	REV: D
	CASE NUMBER: 1317A-04	26 OCT 2006
	STANDARD: NON-JEDEC	

CASE 1317A-04
ISSUE D
SUPER SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS

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	CASE NUMBER: 1317A-04	26 OCT 2006	
	STANDARD: NON-JEDEC		

CASE 1317A-04
ISSUE D
SUPER SMALL OUTLINE PACKAGE

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